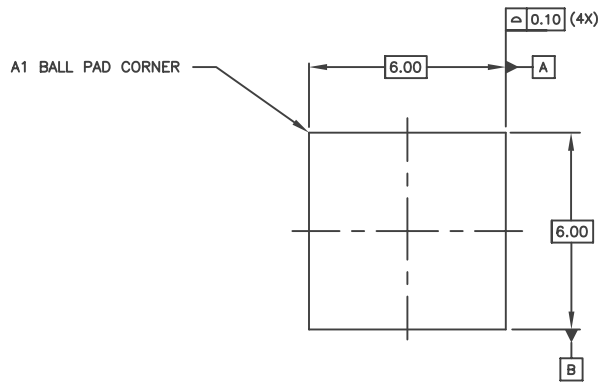
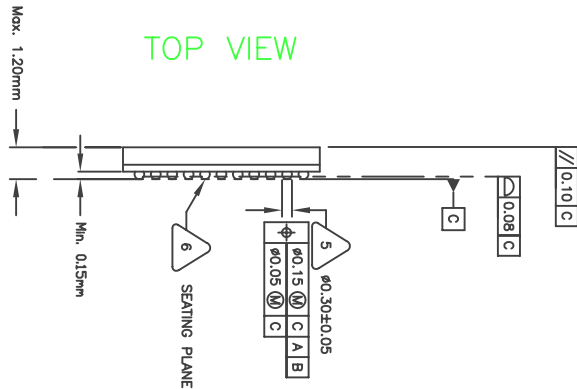


## REVISIONS

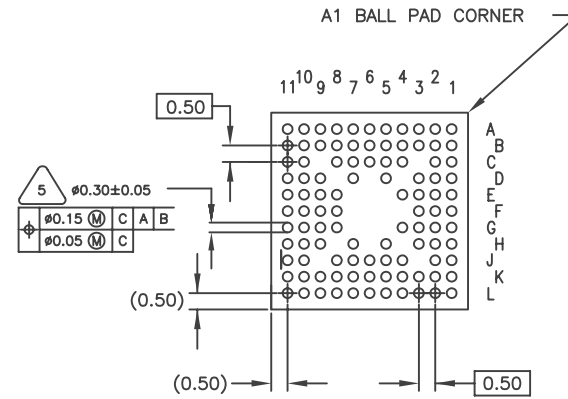
ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
	A		NEW RELEASE	10/12/06	RUTH LIN
	B		Change labeling on overall package height and the collapsed ball height	02/13/07	RUTH LIN



TOP VIEW



SIDE VIEW



BOTTOM VIEW

101 SOLDER BALLS

7. REFERENCE SPECIFICATIONS:  
 A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.  
 B. AAWW SPEC #001-0519-2062: MARKING.



6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 121.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 11 X 11.
2. THE BASIC SOLDER BALL GRID PITCH IS 0.50mm.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

DRAWN RUTH LIN	DATE 10/12/06	<b>QUICKLOGIC CORP</b>
APPROVED BY K.H. THE	DATE 10/14/06	
TF-BGA, 6x6x1.2mm 2L, PU101 BALL, 0.50mm PITCH		
PROJECTION 	SCALE N/A	DWG NO 03-015-85
REFERENCE PACKAGE OUTLINES	QUICKLOGIC PKG CODE: PU101	REV B
		SHEET 1 OF 1